

Title (en)

MULTIPLE DIE FACE-DOWN STACKING FOR TWO OR MORE DIE

Title (de)

NACH UNTEN ZEIGENDE MEHRFACHCHIPSTAPELUNG FÜR ZWEI ODER MEHR CHIPS

Title (fr)

EMPLIAGE DE MULTIPLES PUCES FACE AU-DESSOUS POUR DEUX PUCES OU PLUS DE DEUX PUCES

Publication

EP 2880685 A1 20150610 (EN)

Application

EP 13750213 A 20130801

Priority

- US 201213565613 A 20120802
- US 201313741890 A 20130115
- US 2013053240 W 20130801

Abstract (en)

[origin: WO2014022675A1] A microelectronic assembly (100) can include a substrate (102) having first and second surfaces (104, 106) each extending in first and second transverse directions D1, D2, a peripheral edge (3) extending in the second direction, first and second openings (116, 126) extending between the first and second surfaces, and a peripheral region P1 of the second surface extending between the peripheral edge and one of the openings. The assembly (100) can also include a first microelectronic element (136) having an edge (146) extending between front and rear surfaces (140, 138) thereof and a second microelectronic element (153) having a front surface (157) facing the rear surface of the first microelectronic element and projecting beyond the edge. The assembly (100) can also include a plurality of terminals (110) exposed at the second surface (106), at least one of the terminals (110a) being disposed at least partially within the peripheral region P1.

IPC 8 full level

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CPC (source: EP KR)

H01L 23/13 (2013.01 - EP KR); **H01L 23/49816** (2013.01 - EP KR); **H01L 23/50** (2013.01 - EP); **H01L 24/05** (2013.01 - KR); **H01L 24/06** (2013.01 - KR); **H01L 24/32** (2013.01 - KR); **H01L 24/48** (2013.01 - KR); **H01L 24/49** (2013.01 - KR); **H01L 24/73** (2013.01 - KR); **H01L 25/0657** (2013.01 - EP KR); **H01L 24/05** (2013.01 - EP); **H01L 24/06** (2013.01 - EP); **H01L 24/32** (2013.01 - EP); **H01L 24/48** (2013.01 - EP); **H01L 24/49** (2013.01 - EP); **H01L 24/73** (2013.01 - EP); **H01L 2224/05555** (2013.01 - EP); **H01L 2224/06136** (2013.01 - EP); **H01L 2224/32145** (2013.01 - EP); **H01L 2224/32225** (2013.01 - EP); **H01L 2224/48091** (2013.01 - EP); **H01L 2224/4824** (2013.01 - EP); **H01L 2224/49095** (2013.01 - EP); **H01L 2224/49175** (2013.01 - EP); **H01L 2224/73215** (2013.01 - EP); **H01L 2924/00014** (2013.01 - EP); **H01L 2924/15311** (2013.01 - EP); **H01L 2924/181** (2013.01 - EP)

Citation (search report)

See references of WO 2014022675A1

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